

L Number	Hits	Search Text	DB	Time stamp
1	5	29/832.ccls. and solder near paste and cream	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 10:38
2	73	module adj connection and pcb and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 10:45
3	3	module adj connection and pcb and ball and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 10:46
4	18	module adj connection and pcb and ball and (29/832; 29/833 ; 29/840 ; 29/834 ; 29/740 ; 29/841 ; 29/854 ; 29/855 ; 29/DIG.1 ; 174/176 ; 174/189 ; 174/52.1 ; 228/178 ; 228/179.1 ; 228/180.1 ; 361/760 ; 361/764 ; 361/719 ; 257/697 ; 257/737 ; 257/739 ; 257/777-779).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 10:47
5	29	module adj connection and pcb and ball and (29/832; 29/833 ; 29/840 ; 29/834 ; 29/740 ; 29/841 ; 29/854 ; 29/855 ; 29/DIG.1 ; 174/176 ; 174/189 ; 174/52.1 ; 228/178 ; 228/179.1 ; 228/180.1 ; 361/760 ; 361/764 ; 361/719 ; 257/697 ; 257/737 ; 257/739 ; 257/777-779; 361/760, 257/664 , 257/724 , 257/728 , 257/924 , 333/246 , 333/247 , 361/780 , 361/782 , 361/783).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 10:55
6	0	Bourrierer near francis .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 10:56
7	51	Bourrieres near francis .inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 11:01
8	6	("5346118" "5539153" "5587342" "5658827" "5872051" "5934545").PN.	USPAT	2004/06/24 10:59
9	0	Bourrieres near francis .inv. and 29/832.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 11:02

10	1	Bourrieres near francis .inv. and module and interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/24 11:03
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	Title	Current OR
1	Method of forming an electrical interconnect	438/125
2	Ball placement method and apparatus for forming a ball grid array	228/191
3	Process for transferring material to semiconductor chip conductive pads using a transfer substrate	438/616
4	Method for forming solder balls on a substrate	228/180.22
5	Method of bumping substrates by contained paste deposition	174/260
6	Surface mount solder assembly of leadless integrated circuit packages to substrates	228/180.22

	Current XRef
1	257/E21.508; 257/E23.021; 430/315; 438/613; 438/96
2	228/246; 228/254; 228/41; 257/E21.508
3	228/180.22; 257/E21.503; 257/E21.508; 257/E21.511; 257/E23.021; 257/E23.061; 257/E23.067; 257/E23.068
4	427/96; 438/125; 438/615
5	174/259; 228/180.1; 257/E21.503; 257/E21.508; 257/E23.021; 257/E23.069; 29/832
6	228/248.1; 228/254; 257/E21.511; 427/191; 427/383.7